Product Bulletin

Material Solutions

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Flip Chip Application Solutions...

CMI# GPC251A/B

Conductive Adhesives

Two-part room temperature curing, silver filled epoxy adhesive.

Uses: for making electrical and mechanical attachments on electrical components and devices.

CMI# 118-06

Conductive Adhesive

Available in pad-printable (PP), syringe dispensable (SD), screen-printable (SP) and stencible (ST) B-Stageable electrically conductive epoxy die attach adhesive

Resistant to abrasion and scratching.

Uses: bonding capacitors to lead frames, die attach, assembling electrical and electronic components, and mounting devices to flexible and rigid circuitry.

CMI# GPC352-1A/ B-187/119-44

Conductive Adhesives

Two-part, heat curing, silver filled epoxy adhesive. 199-44 provides a longer pot life.

Excellent adhesion to ITO sputtered surfaces.

Uses: Bonding surface mount component to rigid PC boards, die attach, attachment of electrical and electronic components and heat sink attachements.

CMI# 121-20A/B

Anisotropic Conductive Adhesive

A two-part, low temperature curing, anisotropically conductive epoxy adhesive.

Uses: conductive splicing of ribbon cables, bonding of flex circuits to PC boards, E.L. panels and touch panels, and bonding of electrical components in applications where short circuits between closely spaced contact pads are a concern.

. . . Underfill Materials

CMI# 120-27A/B-187

Underfill Material

A black, low viscocity, two-component, under fill, epoxy potting and encapsulating compound.

Releases entrapped air rapidly during cure resulting in a smooth, pinhole free surface.

Uses: encapsulating, potting, under filling and bonding of electronics where lower shrinkage and better conductivity is required.

CMI# 113-33A/B

Underfill Material

A sag resistant black, glob top, flame-out, two-component, epoxy potting and encapsulating compound.

Crack resistant with a working life greater than thirty minutes.

Uses: potting, encapsulating, glob topping, under filling and bonding of electronics.

CMI# 116-04A/B-187

Underfill Material

A low viscosity, two-component under fill potting and encapsulating compound.

Designed for requiring extremely good thermal conductivity.

Uses: potting, encapsulating, under filling and bonding of electronics.

CMI# 102-12A/B-187

Underfill Material

A thermal cycle resistant, black epoxy compound with an excellent resistance to shock. Requires mild heat cure.

Has a working life of greater than four hours.

Uses: encapsulating, potting, glob topping, underfilling and bonding of electronics.

For more information, you can contact us at:

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